



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TC 1700

Re the Application of: OOHASHI, Takeshi et al.

Group Art Unit: 1752

Serial No.: 09/926,033

Examiner: Yvette C. Thornton

Filed: November 7, 2001

P.T.O. Confirmation No.: 3978

FOR: PHOTSENSITIVE RESIN COMPOSITION, PHOTSENSITIVE ELEMENT
USING THE SAME, PROCESS FOR PRODUCING RESIST PATTERN AND PROCESS
FOR PRODUCING PRINTED WIRING BOARD

12/

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 22, 2003

Sir:

In response to the Office Action dated May 19, 2003, Applicants request favorable reconsideration of the above-identified application. Claims 1-26 are pending.

Applicants' Response to the Rejection of Claims 1, 4-13, 16-18 and 21-23 Under 35 U.S.C. 102(b) as Being Anticipated by Lipson (EP 128014 A2).

Claims 1, 4-13, 16-18 and 21-23 stand rejected under §102 as being anticipated by *Lipson*. Applicants respectfully traverse and request withdrawal of the rejection based on the following comparison of the reference and present invention.

Lipson generally discloses a photopolymerizable composition on pages 4-6, in particular the addition polymerizable material (A) containing acrylate (i) is disclosed on page 4, line 20, to page 5, line 4. *Lipson's* formula in column 4, line 22, as one of a great number of possibilities when *Lipson's* m is 2 to 6, when *Lipson's* n is 6 to 12, and when *Lipson's* R₂ is a phenyl group encompass